

High-Speed CMOS Logic 8-Bit Shift Register with Input Storage

Features

- Buffered Inputs
- Asynchronous Parallel Load
- Fanout (Over Temperature Range)
 - Standard Outputs 10 LSTTL Loads
 - Bus Driver Outputs 15 LSTTL Loads
- Wide Operating Temperature Range . . . -55°C to 125°C
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- HC Types
 - 2V to 6V Operation
 - High Noise Immunity: $N_{IL} = 30\%$, $N_{IH} = 30\%$ of V_{CC} at $V_{CC} = 5V$
- HCT Types
 - 4.5V to 5.5V Operation
 - Direct LSTTL Input Logic Compatibility, $V_{IL} = 0.8V$ (Max), $V_{IH} = 2V$ (Min)
 - CMOS Input Compatibility, $I_I \leq 1\mu A$ at V_{OL} , V_{OH}

Description

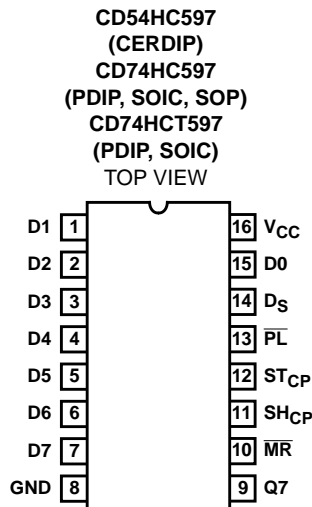
The 'HC597 and CD74HCT597 are high-speed silicon gate CMOS devices that are pin-compatible with the LSTTL 597 devices. Each device consists of an 8-flip-flop input register and an 8-bit parallel-in/serial-in, serial-out shift register. Each register is controlled by its own clock. A "low" on the parallel load input (\overline{PL}) shifts parallel stored data asynchronously into the shift register. A "low" master input (\overline{MR}) clears the shift register. Serial input data can also be synchronously shifted through the shift register when \overline{PL} is high.

Ordering Information

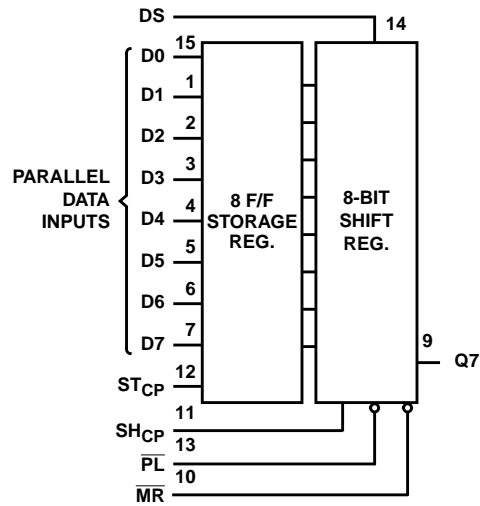
| PART NUMBER | TEMP. RANGE (°C) | PACKAGE |
|---------------|------------------|--------------|
| CD54HC597F3A | -55 to 125 | 16 Ld CERDIP |
| CD74HC597E | -55 to 125 | 16 Ld PDIP |
| CD74HC597M | -55 to 125 | 16 Ld SOIC |
| CD74HC597MT | -55 to 125 | 16 Ld SOIC |
| CD74HC597M96 | -55 to 125 | 16 Ld SOIC |
| CD74HC597NSR | -55 to 125 | 16 Ld SOP |
| CD74HCT597E | -55 to 125 | 16 Ld PDIP |
| CD74HCT597M | -55 to 125 | 16 Ld SOIC |
| CD74HCT597MT | -55 to 125 | 16 Ld SOIC |
| CD74HCT597M96 | -55 to 125 | 16 Ld SOIC |

NOTE: When ordering, use the entire part number. The suffixes 96 and R denote tape and reel. The suffix T denotes a small-quantity reel of 250.

Pinout



Functional Diagram



FUNCTION TABLE

| ST _{CP} | SH _{CP} | \overline{PL} | \overline{MR} | FUNCTION |
|------------------|------------------|-----------------|-----------------|---|
| ↑ | X | X | X | Data Loaded to Input Flip-Flops |
| ↑ | X | L | H | Data Loaded from Inputs to Shift Register |
| No Clock Edge | X | L | H | Data Transferred from Input Flip-Flops to Shift Register |
| X | X | L | L | Invalid Logic, State of Shift Register Indeterminate when Signals Removed |
| X | X | H | L | Shift Register Cleared |
| X | ↑ | H | H | Shift Register Clocked $Q_n = Q_{n-1}$, $Q_0 = D_S$ |

H = High Voltage Level, L = Low Voltage Level, X = Don't Care, ↑ = Transition from Low to High CP Level

CD54HC597, CD74HC597, CD74HCT597

Absolute Maximum Ratings

| | |
|--|-------------|
| DC Supply Voltage, V_{CC} | -0.5V to 7V |
| DC Input Diode Current, I_{IK} | |
| For $V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$ | $\pm 20mA$ |
| DC Output Diode Current, I_{OK} | |
| For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$ | $\pm 20mA$ |
| DC Drain Current, per Output, I_O | |
| For $-0.5V < V_O < V_{CC} + 0.5V$ | $\pm 25mA$ |
| DC Output Source or Sink Current per Output Pin, I_O | |
| For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$ | $\pm 25mA$ |
| DC V_{CC} or Ground Current, I_{CC} | $\pm 50mA$ |

Thermal Information

| | |
|--|----------------------------------|
| Thermal Resistance (Typical, Note 1) | θ_{JA} (°C/W) |
| E (PDIP) Package | 67 |
| M (SOIC) Package | 73 |
| NS (SOP) Package | 64 |
| Maximum Junction Temperature | 150°C |
| Maximum Storage Temperature Range | -65°C to 150°C |
| Maximum Lead Temperature (Soldering 10s) | 300°C (SOIC - Lead Tips Only) |

Operating Conditions

| | |
|--|----------------|
| Temperature Range, T_A | -55°C to 125°C |
| Supply Voltage Range, V_{CC} | |
| HC Types | .2V to 6V |
| DC Input or Output Voltage, V_I, V_O | 0V to V_{CC} |
| Input Rise and Fall Time | |
| 2V | 1000ns (Max) |
| 4.5V | 500ns (Max) |
| 6V | 400ns (Max) |

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. The package thermal impedance is calculated in accordance with JESD 51-7.

DC Electrical Specifications

| PARAMETER | SYMBOL | TEST CONDITIONS | | V_{CC} (V) | 25°C | | | -40°C TO 85°C | | -55°C TO 125°C | | UNITS |
|---|----------|----------------------|------------|--------------|------|-----|-----------|---------------|---------|----------------|---------|---------|
| | | V_I (V) | I_O (mA) | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| HC TYPES | | | | | | | | | | | | |
| High Level Input Voltage | V_{IH} | - | - | 2 | 1.5 | - | - | 1.5 | - | 1.5 | - | V |
| | | | | 4.5 | 3.15 | - | - | 3.15 | - | 3.15 | - | V |
| | | | | 6 | 4.2 | - | - | 4.2 | - | 4.2 | - | V |
| Low Level Input Voltage | V_{IL} | - | - | 2 | - | - | 0.5 | - | 0.5 | - | 0.5 | V |
| | | | | 4.5 | - | - | 1.35 | - | 1.35 | - | 1.35 | V |
| | | | | 6 | - | - | 1.8 | - | 1.8 | - | 1.8 | V |
| High Level Output Voltage CMOS Loads | V_{OH} | V_{IH} or V_{IL} | -0.02 | 2 | 1.9 | - | - | 1.9 | - | 1.9 | - | V |
| | | | -0.02 | 4.5 | 4.4 | - | - | 4.4 | - | 4.4 | - | V |
| | | | -0.02 | 6 | 5.9 | - | - | 5.9 | - | 5.9 | - | V |
| High Level Output Voltage TTL Loads | V_{OH} | V_{IH} or V_{IL} | - | - | - | - | - | - | - | - | - | V |
| | | | -4 | 4.5 | 3.98 | - | - | 3.84 | - | 3.7 | - | V |
| | | | -5.2 | 6 | 5.48 | - | - | 5.34 | - | 5.2 | - | V |
| Low Level Output Voltage CMOS Loads | V_{OL} | V_{IH} or V_{IL} | 0.02 | 2 | - | - | 0.1 | - | 0.1 | - | 0.1 | V |
| | | | 0.02 | 4.5 | - | - | 0.1 | - | 0.1 | - | 0.1 | V |
| | | | 0.02 | 6 | - | - | 0.1 | - | 0.1 | - | 0.1 | V |
| Low Level Output Voltage TTL Loads | V_{OL} | V_{IH} or V_{IL} | - | - | - | - | - | - | - | - | - | V |
| | | | 4 | 4.5 | - | - | 0.26 | - | 0.33 | - | 0.4 | V |
| | | | 5.2 | 6 | - | - | 0.26 | - | 0.33 | - | 0.4 | V |
| Input Leakage Current | I_I | V_{CC} or GND | - | 6 | - | - | ± 0.1 | - | ± 1 | - | ± 1 | μA |

CD54HC597, CD74HC597, CD74HCT597

DC Electrical Specifications (Continued)

| PARAMETER | SYMBOL | TEST CONDITIONS | | V _{CC} (V) | 25°C | | | -40°C TO 85°C | | -55°C TO 125°C | | UNITS |
|--|---------------------------|------------------------------------|---------------------|---------------------|------|-----|------|---------------|------|----------------|-----|-------|
| | | V _I (V) | I _O (mA) | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| Quiescent Device Current | I _{CC} | V _{CC} or GND | 0 | 6 | - | - | 8 | - | 80 | - | 160 | μA |
| HCT TYPES | | | | | | | | | | | | |
| High Level Input Voltage | V _{IH} | - | - | 4.5 to 5.5 | 2 | - | - | 2 | - | 2 | - | V |
| Low Level Input Voltage | V _{IL} | - | - | 4.5 to 5.5 | - | - | 0.8 | - | 0.8 | - | 0.8 | V |
| High Level Output Voltage CMOS Loads | V _{OH} | V _{IH} or V _{IL} | -0.02 | 4.5 | 4.4 | - | - | 4.4 | - | 4.4 | - | V |
| High Level Output Voltage TTL Loads | | | -4 | 4.5 | 3.98 | - | - | 3.84 | - | 3.7 | - | V |
| Low Level Output Voltage CMOS Loads | V _{OL} | V _{IH} or V _{IL} | 0.02 | 4.5 | - | - | 0.1 | - | 0.1 | - | 0.1 | V |
| Low Level Output Voltage TTL Loads | | | 4 | 4.5 | - | - | 0.26 | - | 0.33 | - | 0.4 | V |
| Input Leakage Current | I _I | V _{CC} and GND | 0 | 5.5 | - | | ±0.1 | - | ±1 | - | ±1 | μA |
| Quiescent Device Current | I _{CC} | V _{CC} or GND | 0 | 5.5 | - | - | 8 | - | 80 | - | 160 | μA |
| Additional Quiescent Device Current Per Input Pin: 1 Unit Load | ΔI _{CC} (Note 2) | V _{CC} -2.1 | - | 4.5 to 5.5 | - | 100 | 360 | - | 450 | - | 490 | μA |

NOTE:

2. For dual-supply systems theoretical worst case (V_I = 2.4V, V_{CC} = 5.5V) specification is 1.8mA.

HCT Input Loading Table

| INPUT | UNIT LOADS |
|-------------------------------------|------------|
| D _S | 0.2 |
| D _n | 0.3 |
| PL, MR | 1.5 |
| ST _{CP} , SH _{CP} | 1.5 |

NOTE: Unit Load is ΔI_{CC} limit specified in DC Electrical Specifications Table, e.g., 360μA max. at 25°C.

Prerequisite for Switching Specifications

| PARAMETER | SYMBOL | V _{CC} (V) | 25°C | | | -40°C TO 85°C | | | -55°C TO 125°C | | | UNITS |
|----------------------------|------------------|---------------------|------|-----|-----|---------------|-----|-----|----------------|-----|-----|-------|
| | | | MIN | TYP | MAX | MIN | TYP | MAX | MIN | TYP | MAX | |
| HC TYPES | | | | | | | | | | | | |
| SH _{CP} Frequency | f _{MAX} | 2 | 6 | - | - | 5 | - | - | 4 | - | - | MHz |
| | | 4.5 | 30 | - | - | 25 | - | - | 20 | - | - | MHz |
| | | 6 | 35 | - | - | 29 | - | - | 23 | - | - | MHz |

CD54HC597, CD74HC597, CD74HCT597

Prerequisite for Switching Specifications (Continued)

| PARAMETER | SYMBOL | V _{CC} (V) | 25°C | | | -40°C TO 85°C | | | -55°C TO 125°C | | | UNITS |
|--|------------------|---------------------|------|-----|-----|---------------|-----|-----|----------------|-----|-----|-------|
| | | | MIN | TYP | MAX | MIN | TYP | MAX | MIN | TYP | MAX | |
| SH _{CP} Pulse Width | t _W | 2 | 80 | - | - | 100 | - | - | 120 | - | - | ns |
| | | 4.5 | 16 | - | - | 20 | - | - | 24 | - | - | ns |
| | | 6 | 14 | - | - | 17 | - | - | 20 | - | - | ns |
| ST _{CP} Pulse Width | t _W | 2 | 60 | - | - | 75 | - | - | 90 | - | - | ns |
| | | 4.5 | 12 | - | - | 15 | - | - | 18 | - | - | ns |
| | | 6 | 10 | - | - | 13 | - | - | 15 | - | - | ns |
| MR Pulse Width | t _W | 2 | 80 | - | - | 100 | - | - | 120 | - | - | ns |
| | | 4.5 | 16 | - | - | 20 | - | - | 24 | - | - | ns |
| | | 6 | 14 | - | - | 17 | - | - | 20 | - | - | ns |
| PL Pulse Width | t _W | 2 | 70 | - | - | 90 | - | - | 105 | - | - | ns |
| | | 4.5 | 14 | - | - | 18 | - | - | 21 | - | - | ns |
| | | 6 | 12 | - | - | 15 | - | - | 18 | - | - | ns |
| ST _{CP} to SH _{CP} Setup Time | t _{SU} | 2 | 100 | - | - | 125 | - | - | 150 | - | - | ns |
| | | 4.5 | 20 | - | - | 25 | - | - | 30 | - | - | ns |
| | | 6 | 17 | - | - | 21 | - | - | 26 | - | - | ns |
| D _S to SH _{CP} Setup Time D _N to ST _{CP} Setup Time | t _{SU} | 2 | 50 | - | - | 65 | - | - | 75 | - | - | ns |
| | | 4.5 | 10 | - | - | 13 | - | - | 15 | - | - | ns |
| | | 6 | 9 | - | - | 11 | - | - | 13 | - | - | ns |
| ST _{CP} to SH _{CP} Setup Time | t _H | 2 | 0 | - | - | 0 | - | - | 0 | - | - | ns |
| | | 4.5 | 0 | - | - | 0 | - | - | 0 | - | - | ns |
| | | 6 | 0 | - | - | 0 | - | - | 0 | - | - | ns |
| D _S to SH _{CP} Hold Time D _N to ST _{CP} Hold Time | t _H | 2 | 3 | - | - | 3 | - | - | 3 | - | - | ns |
| | | 4.5 | 3 | - | - | 3 | - | - | 3 | - | - | ns |
| | | 6 | 3 | - | - | 3 | - | - | 3 | - | - | ns |
| MR to SH _{CP} Removal Time | t _{REM} | 2 | 3 | - | - | 3 | - | - | 3 | - | - | ns |
| | | 4.5 | 3 | - | - | 3 | - | - | 3 | - | - | ns |
| | | 6 | 3 | - | - | 3 | - | - | 3 | - | - | ns |
| HCT TYPES | | | | | | | | | | | | |
| SH _{CP} Frequency | f _{MAX} | 4.5 | 25 | - | - | 20 | - | - | 16 | - | - | MHz |
| SH _{CP} Pulse Width | t _W | 4.5 | 20 | - | - | 25 | - | - | 30 | - | - | ns |
| ST _{CP} Pulse Width | t _W | 4.5 | 13 | - | - | 16 | - | - | 20 | - | - | ns |
| MR Pulse Width | t _W | 4.5 | 18 | - | - | 23 | - | - | 27 | - | - | ns |
| PL Pulse Width | t _W | 4.5 | 16 | - | - | 20 | - | - | 24 | - | - | ns |
| ST _{CP} to SH _{CP} Setup Time | t _{SU} | 4.5 | 24 | - | - | 30 | - | - | 36 | - | - | ns |

CD54HC597, CD74HC597, CD74HCT597

Prerequisite for Switching Specifications (Continued)

| PARAMETER | SYMBOL | V _{CC} (V) | 25°C | | | -40°C TO 85°C | | | -55°C TO 125°C | | | UNITS |
|--|------------------|---------------------|------|-----|-----|---------------|-----|-----|----------------|-----|-----|-------|
| | | | MIN | TYP | MAX | MIN | TYP | MAX | MIN | TYP | MAX | |
| D _S to SH _{CP} Setup Time D _n to ST _{CP} Setup Time | t _H | 4.5 | 10 | - | - | 13 | - | - | 15 | - | - | ns |
| ST _{CP} to SH _{CP} Hold Time | t _H | 4.5 | 0 | - | - | 0 | - | - | 0 | - | - | ns |
| D _S to SH _{CP} Hold Time D _n to ST _{CP} Hold Time | t _H | 4.5 | 3 | - | - | 3 | - | - | 3 | - | - | ns |
| MR to SH _{CP} Removal Time | t _{REM} | 4.5 | 10 | - | - | 13 | - | - | 15 | - | - | ns |

Switching Specifications Input t_r, t_f = 6ns

| PARAMETER | SYMBOL | TEST CONDITIONS | V _{CC} (V) | 25°C | | | -40°C to 85°C | | -55°C to 125°C | | UNITS |
|---|-------------------------------------|-----------------------|---------------------|------|------|-----|---------------|-----|----------------|-----|-------|
| | | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| HC TYPES | | | | | | | | | | | |
| Propagation Delay SH _{CP} to Q7 | t _{PLH} , t _{PHL} | C _L = 50pF | 2 | - | - | 175 | - | 220 | - | 265 | ns |
| | | | 4.5 | - | - | 35 | - | 44 | - | 53 | ns |
| | | C _L = 15pF | 5 | - | 14 | - | - | - | - | - | ns |
| | | C _L = 50pF | 6 | - | - | 30 | - | 37 | - | 45 | ns |
| $\overline{\text{PL}}$ to Q7 | t _{PLH} , t _{PHL} | C _L = 50pF | 2 | - | - | 200 | - | 250 | - | 300 | ns |
| | | | 4.5 | - | - | 40 | - | 50 | - | 60 | ns |
| | | C _L = 15pF | 5 | - | 17 | - | - | - | - | - | ns |
| | | C _L = 50pF | 6 | - | - | 34 | - | 43 | - | 51 | ns |
| ST _{CP} to Q7 | t _{PLH} , t _{PHL} | C _L = 50pF | 2 | - | - | 240 | - | 300 | - | 360 | ns |
| | | | 4.5 | - | - | 48 | - | 60 | - | 72 | ns |
| | | C _L = 15pF | 5 | - | 20 | - | - | - | - | - | ns |
| | | C _L = 50pF | 6 | - | - | 41 | - | 51 | - | 61 | ns |
| $\overline{\text{MR}}$ to Q7 | t _{PLH} , t _{PHL} | C _L = 50pF | 2 | - | - | 175 | - | 220 | - | 265 | ns |
| | | | 4.5 | - | - | 35 | - | 44 | - | 53 | ns |
| | | C _L = 15pF | 5 | - | 14 | - | - | - | - | - | ns |
| | | C _L = 50pF | 6 | - | - | 30 | - | 37 | - | 45 | ns |
| Output Transition Time | t _{TLH} , t _{THL} | C _L = 50pF | 2 | - | - | 75 | - | 95 | - | 110 | ns |
| | | | 4.5 | - | - | 15 | - | 19 | - | 22 | ns |
| | | | 6 | - | - | 13 | - | 16 | - | 19 | ns |
| Input Capacitance | C _I | C _L = 50pF | - | - | - | 10 | - | 10 | - | 10 | pF |
| Power Dissipation Capacitance, (Notes 3, 4) | C _{PD} | - | 5 | - | 13.5 | - | - | - | - | - | pF |
| HCT | | | | | | | | | | | |
| Propagation Delay SH _{CP} to Q7 | t _{PLH} , t _{PHL} | C _L = 50pF | 4.5 | - | - | 38 | - | 48 | - | 57 | ns |
| | | C _L = 15pF | 5 | - | 16 | - | - | - | - | - | ns |
| $\overline{\text{PL}}$ to Q7 | t _{PLH} , t _{PHL} | C _L = 50pF | 4.5 | - | - | 48 | - | 60 | - | 72 | ns |
| | | C _L = 15pF | 5 | - | 20 | - | - | - | - | - | ns |
| ST _{CP} to Q7 | t _{PLH} , t _{PHL} | C _L = 50pF | 4.5 | - | - | 56 | - | 70 | - | 84 | ns |
| | | C _L = 15pF | 5 | - | 23 | - | - | - | - | - | ns |

CD54HC597, CD74HC597, CD74HCT597

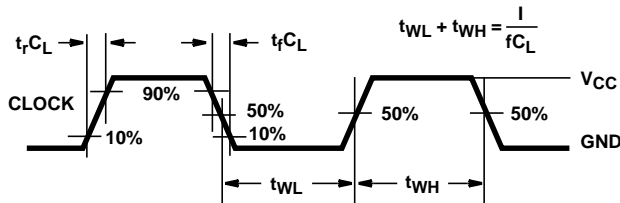
Switching Specifications Input $t_r, t_f = 6\text{ns}$ (Continued)

| PARAMETER | SYMBOL | TEST CONDITIONS | V_{CC} (V) | 25°C | | | -40°C to 85°C | | -55°C to 125°C | | UNITS |
|---|--------------------|---------------------|--------------|------|------|-----|---------------|-----|----------------|-----|-------|
| | | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| \overline{MR} to Q7 | t_{PLH}, t_{PHL} | $C_L = 50\text{pF}$ | 4.5 | - | - | 44 | - | 55 | - | 66 | ns |
| | | $C_L = 15\text{pF}$ | 5 | - | 18 | - | - | - | - | - | ns |
| Output Transition Time | t_{TLH}, t_{THL} | $C_L = 50\text{pF}$ | 4.5 | - | - | 15 | - | 19 | - | 22 | ns |
| Input Capacitance | C_I | $C_L = 50\text{pF}$ | - | - | - | 10 | - | 10 | - | 10 | pF |
| Power Dissipation Capacitance, (Notes 3, 4) | C_{PD} | - | 5 | - | 18.5 | - | - | - | - | - | pF |

NOTES:

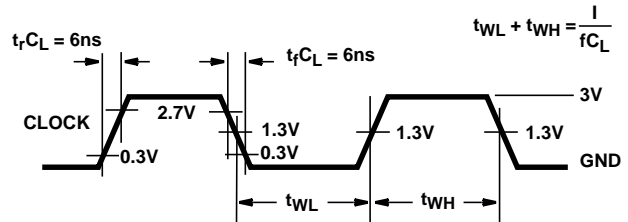
- C_{PD} is used to determine the dynamic power consumption, per package.
- $P_D = C_{PD} V_{CC}^2 f_i + \sum (C_L V_{CC}^2 f_o)$ where: f_i = Input Frequency, f_o = Output Frequency, C_L = Output Load Capacitance, V_{CC} = Supply Voltage.

Test Circuits and Waveforms



NOTE: Outputs should be switching from 10% V_{CC} to 90% V_{CC} in accordance with device truth table. For f_{MAX} , input duty cycle = 50%.

FIGURE 1. HC CLOCK PULSE RISE AND FALL TIMES AND PULSE WIDTH



NOTE: Outputs should be switching from 10% V_{CC} to 90% V_{CC} in accordance with device truth table. For f_{MAX} , input duty cycle = 50%.

FIGURE 2. HCT CLOCK PULSE RISE AND FALL TIMES AND PULSE WIDTH

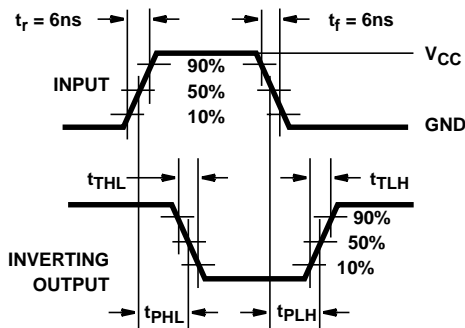


FIGURE 3. HC TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

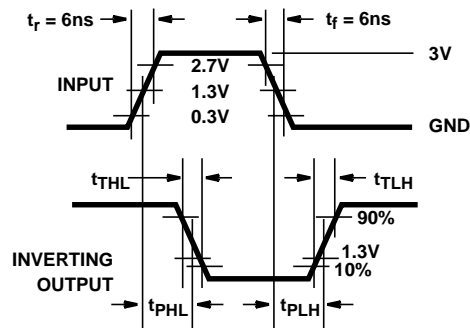


FIGURE 4. HCT TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

Test Circuits and Waveforms (Continued)

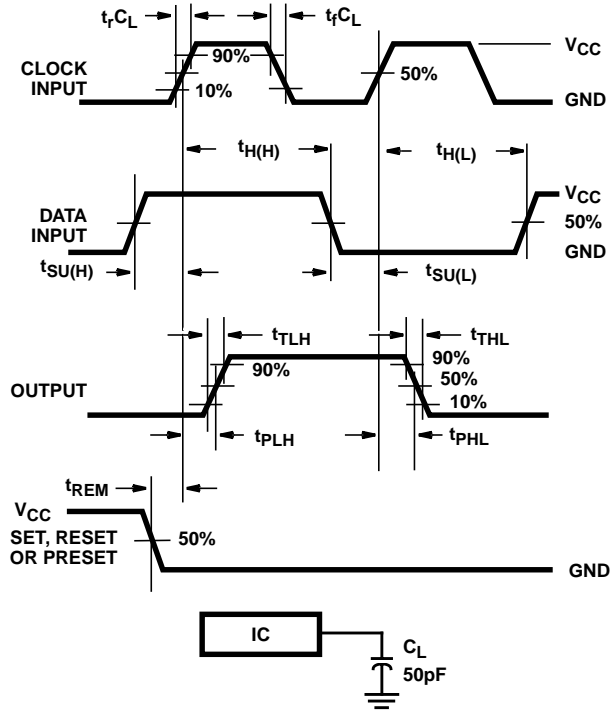


FIGURE 5. HC SETUP TIMES, HOLD TIMES, REMOVAL TIME, AND PROPAGATION DELAY TIMES FOR EDGE TRIGGERED SEQUENTIAL LOGIC CIRCUITS

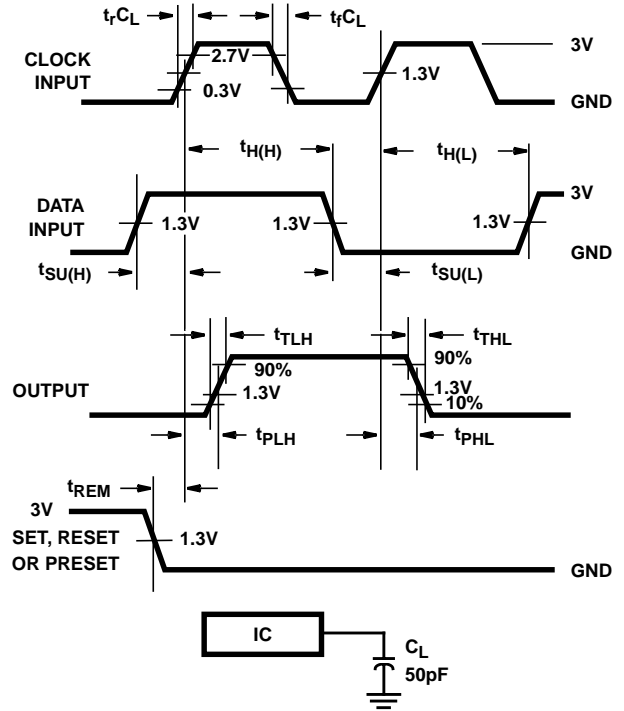
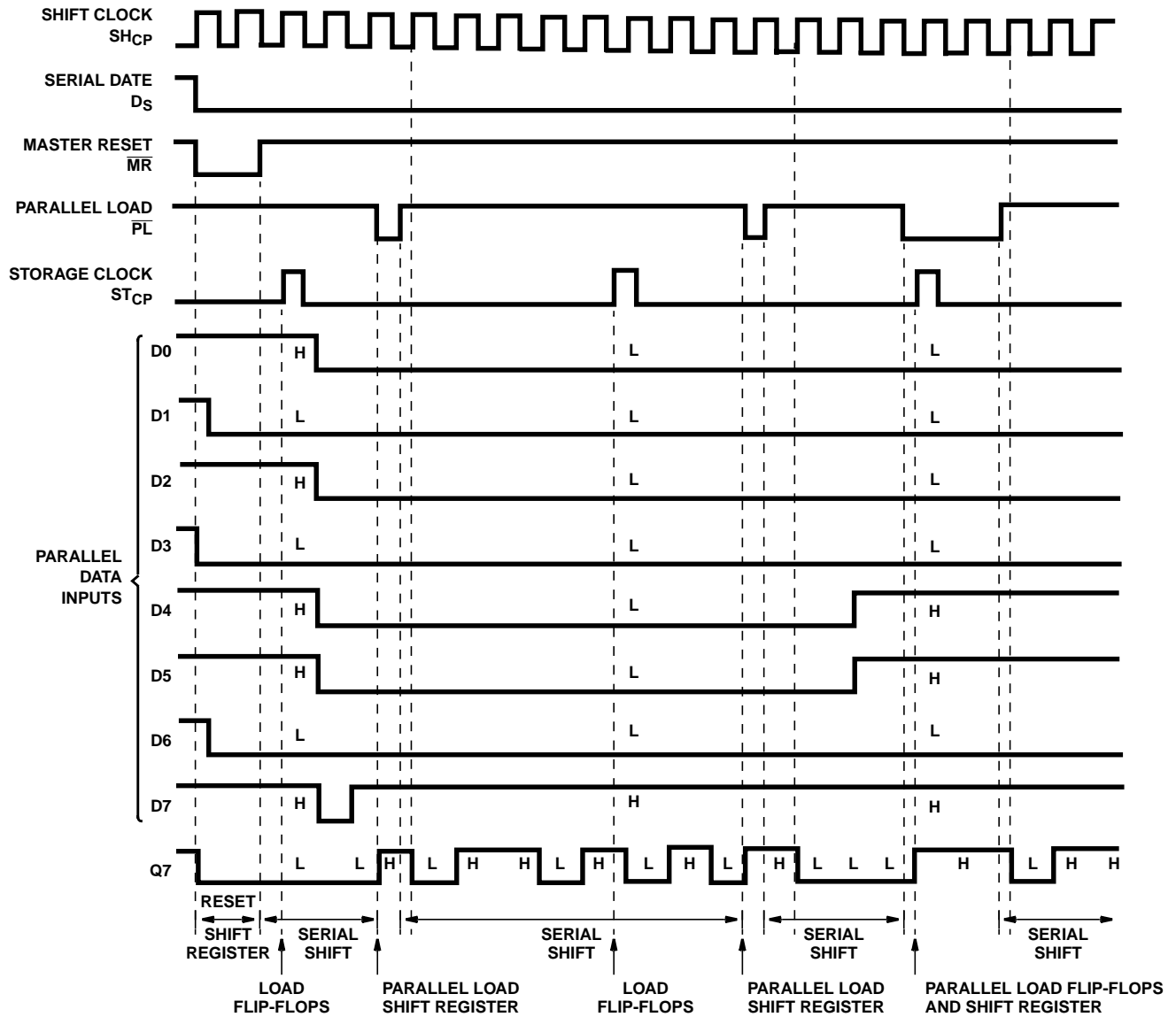


FIGURE 6. HCT SETUP TIMES, HOLD TIMES, REMOVAL TIME, AND PROPAGATION DELAY TIMES FOR EDGE TRIGGERED SEQUENTIAL LOGIC CIRCUITS

Timing Diagram



PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| 5962-8681701EA | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| CD54HC597F3A | ACTIVE | CDIP | J | 16 | 1 | TBD | A42 SNPB | N / A for Pkg Type |
| CD74HC597E | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| CD74HC597EE4 | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| CD74HC597M | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HC597M96 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HC597M96E4 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HC597M96G4 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HC597ME4 | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HC597MG4 | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HC597MT | ACTIVE | SOIC | D | 16 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HC597MTE4 | ACTIVE | SOIC | D | 16 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HC597MTG4 | ACTIVE | SOIC | D | 16 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HC597NSR | ACTIVE | SO | NS | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HC597NSRE4 | ACTIVE | SO | NS | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HC597NSRG4 | ACTIVE | SO | NS | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HCT597E | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| CD74HCT597EE4 | ACTIVE | PDIP | N | 16 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| CD74HCT597M | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HCT597M96 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HCT597M96E4 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HCT597M96G4 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HCT597ME4 | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HCT597MG4 | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HCT597MT | ACTIVE | SOIC | D | 16 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| CD74HCT597MTE4 | ACTIVE | SOIC | D | 16 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| | | | | | | no Sb/Br) | | |
| CD74HCT597MTG4 | ACTIVE | SOIC | D | 16 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| CD74HC597M96 | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |
| CD74HC597NSR | SO | NS | 16 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |
| CD74HCT597M96 | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---------------|--------------|-----------------|------|------|-------------|------------|-------------|
| CD74HC597M96 | SOIC | D | 16 | 2500 | 333.2 | 345.9 | 28.6 |
| CD74HC597NSR | SO | NS | 16 | 2000 | 346.0 | 346.0 | 33.0 |
| CD74HCT597M96 | SOIC | D | 16 | 2500 | 333.2 | 345.9 | 28.6 |

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



| DIM \ PINS ** | 14 | 16 | 18 | 20 |
|---------------|------------------------|------------------------|------------------------|------------------------|
| A | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC |
| B MAX | 0.785 (19,94) | .840 (21,34) | 0.960 (24,38) | 1.060 (26,92) |
| B MIN | — | — | — | — |
| C MAX | 0.300 (7,62) | 0.300 (7,62) | 0.310 (7,87) | 0.300 (7,62) |
| C MIN | 0.245 (6,22) | 0.245 (6,22) | 0.220 (5,59) | 0.245 (6,22) |



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

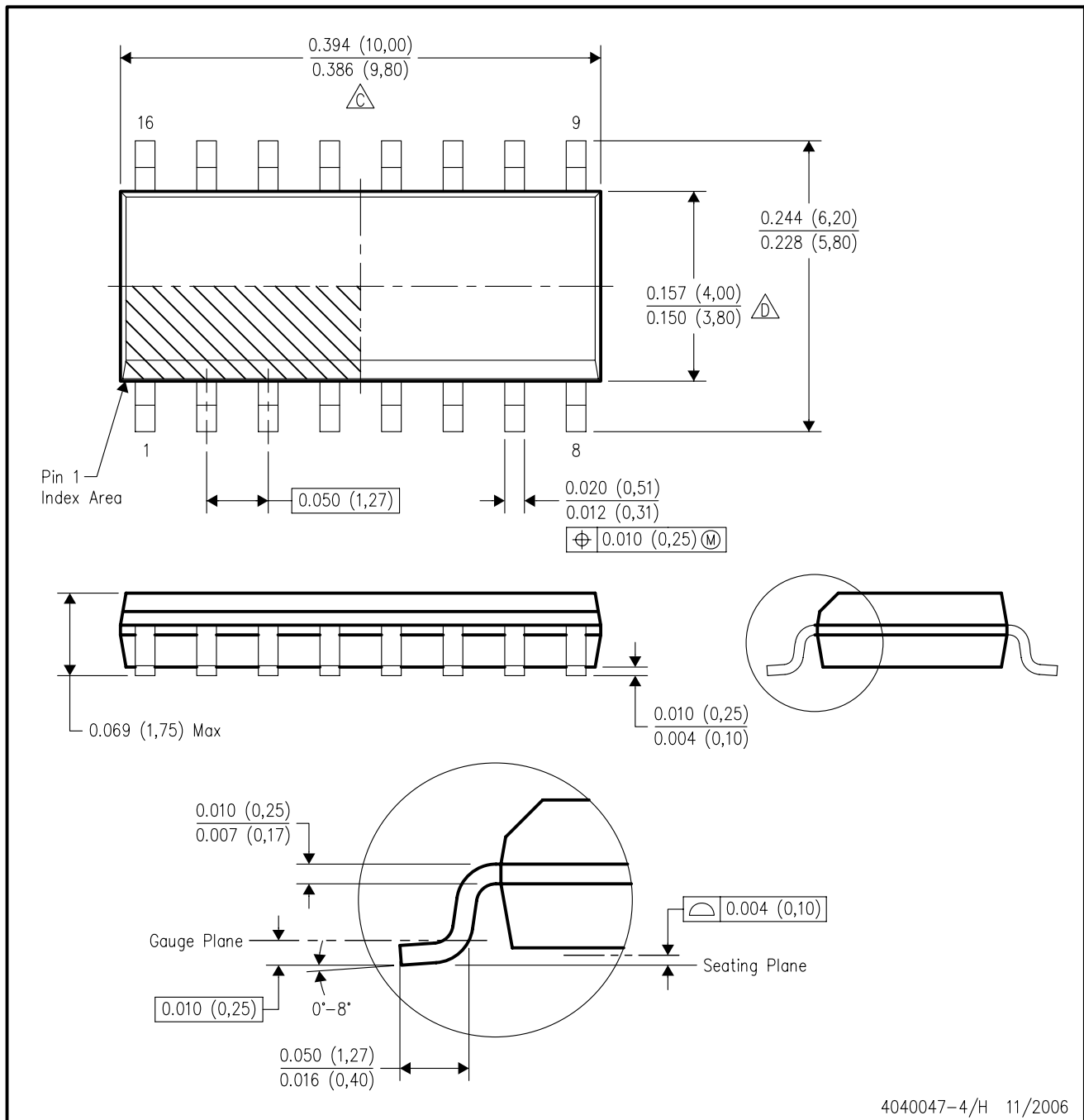
14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AC.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - D The 20 pin end lead shoulder width is a vendor option, either half or full width.

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